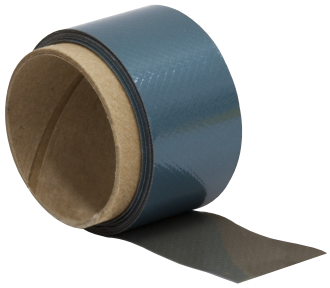
Double-Sided Thermal Tape

TCDT1



Description

The thermally conductive, double-sided tape consists of superior bond strength, pressure-sensitive acrylic adhesive loaded with titanium diboride and applied to an expanded aluminum carrier. The combination of filler, expanded metal, and embossed surface enhances both tape conformability and thermal performance. The thermal tape is embossed with an innovative pattern for maximum conformability and minimal air pockets. The thermal tape offers excellent thermal, mechanical, environmental, and chemical properties. The thermal tape bonds heat sinks and thermal plates to components without the use of clips, screws, or other mechanical fasteners, and using the tape require no additional thermal compound. The thermal tape can be removed after the application without damage to the component.

Specifications



General Specifications	
Construction	
Carrier	Expanded Al
Color	Gray
Thickness	0.009 ± 0.001" (0.229 ± 0.03 mm)
Thermal	
Thermal Impedance @ <1 psi	0.25 °C-in^2/W (1.7 °C-cm^2/W)
Thermal Conductivity	1.40 W/m-K
Electrical	
Voltage Breakdown	N/A
Volume Resistivity	0.013 Ω-cm
Flammability Rating (E140244)	Not Rated
Lap Shear Adhesion	70 psi (0.483 MPa)

Mechanical Specifications		
Die Shear Adhesion		
Aluminum	25 °C	135 psi (0.931 MPa)
	150 °C	25 psi (0.172 MPa)
Copper	25 °C	115 psi (0.793 MPa)
	150 °C	35 psi (0.241 MPa)
Aluminum Oxide Substrate	25 °C	125 psi (0.862 MPa)
	150 °C	40 psi (0.276 MPa)
Creep Adhesion		
25 °C, 12 psi (0.083 MPa)	>50 days	
150 °C, 12 psi (0.083 MPa)	>50 days	
Adhesive CTE, -40 to 150 °C	400 ppm/°C	
Dimensions	1" x 48"	